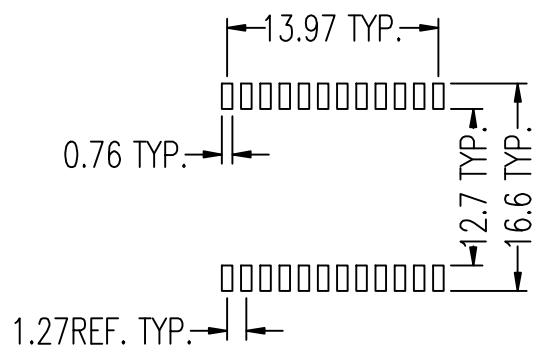
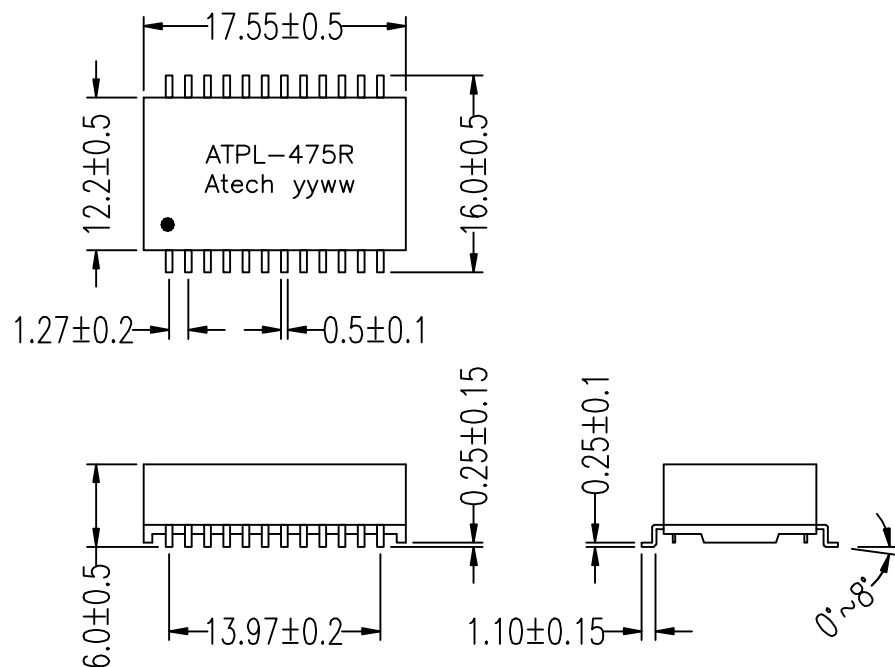
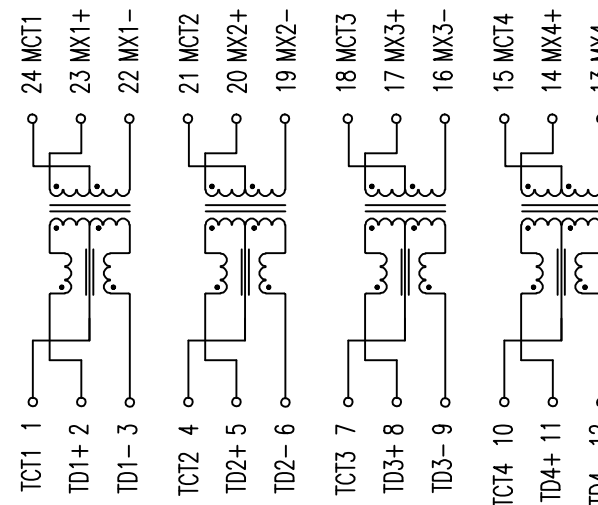




SUGGESTED PAD LAYOUT



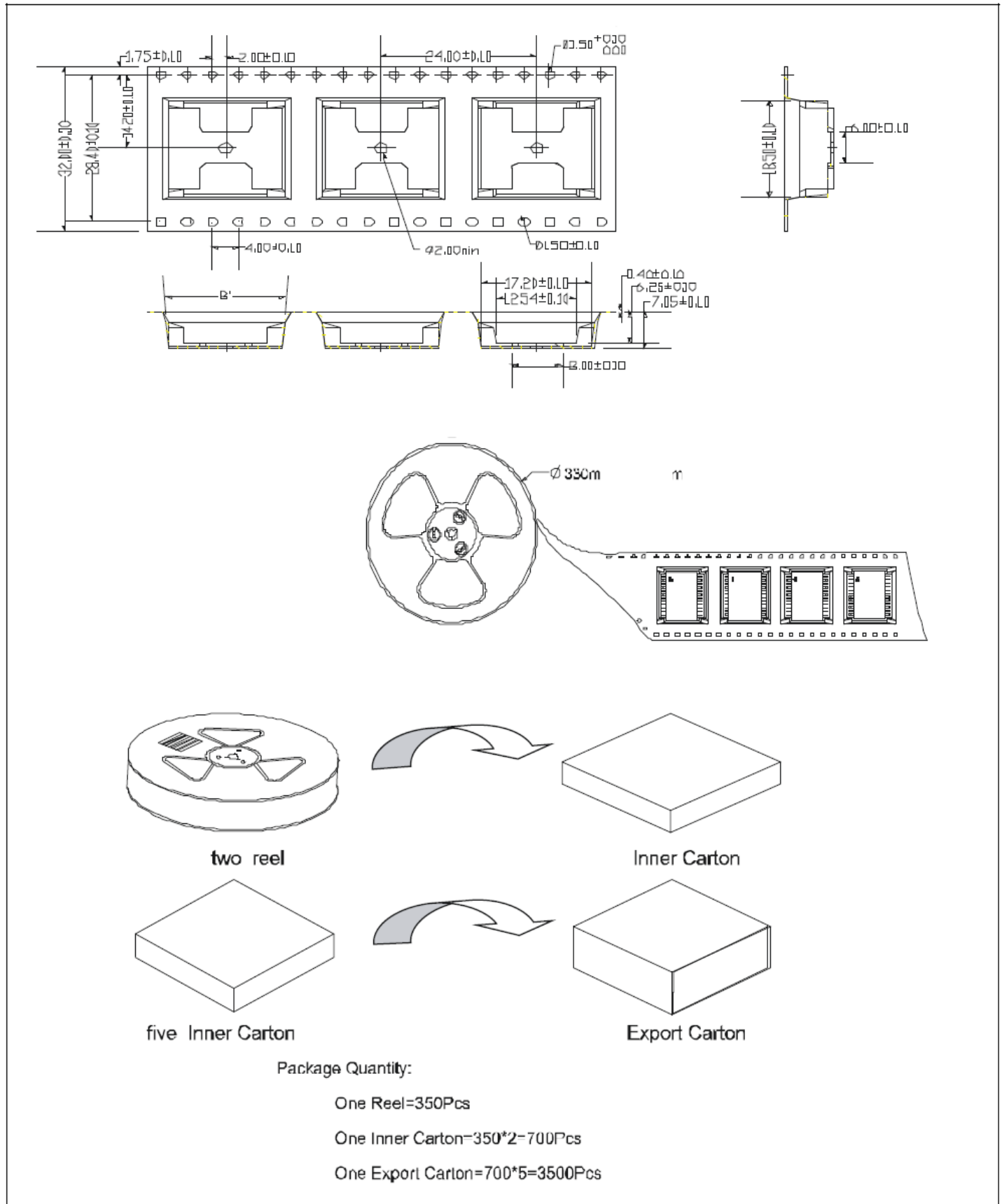
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS :

1. INSULATION HI-POT : 1500 Vrms/1mA ,60Sec.
2. TURN RATIO ($\pm 5\%$) : 1CT : 1CT
3. OCL : (@100kHz, 0.1Vrms) : 120uH MIN
4. CROSS TALK (dB MIN.) : 1-500MHz : -25
5. INSERTION LOSS : 1-200MHz : -1.2dB MAX.
200-300MHz : -1.5dB MAX. 300-400MHz : -2.0dB MAX.
400-500MHz : -3.0dB MAX.
6. RETURN LOSS : 1-100MHz : -18dB MIN. 100-200MHz : -16dB MIN.
200-300MHz : -12dB MIN. 300-400MHz : -10dB MIN.
400-500MHz : -8dB MIN.
7. DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) : 1-500MHz : -25
8. LK(100kHz, 0.1Vrms) : 0.5uH MAX.
9. DCR : 0.9 Ω TYP.
10. Operating temperature : 0°C to +70°C
Storage temperature : -40°C to +85°C

							TITLE 10G BASE-T TRANSFORMER	
							DWG. NO. ATPL-475R	
	RELEASE	12/04 /2014	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	SHEET 1 OF 1
REVISIONS						12/04/14	DRAW SHIRLEY	

3. Package :



Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_{smax} to T_P)	3°C/second max	3°C/second max
Preheat Temperature Min (T_{smin}) Temperature Min (T_{smax}) Time (T_{smin} to T_{smax}) (t_s)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T_L) Time (t_L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T_P)	225°C	260°C
Time within 5°C of actual Peak Temperature (T_P) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max